

## ABSTRACT OF THE DISCLOSURE

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The present invention is directed to a semiconductor chip package that can effectively remove heat from a semiconductor chip, and a method of fabricating the package. In accordance with an embodiment of the invention, the package includes: a substrate having bonding pads; a semiconductor chip having conductive bumps on the front side thereof, the conductive bump contacting the bonding pads; a heat slug bonded to the backside of the semiconductor chip; and a solder film which makes the bonding between the heat slug and the backside of the semiconductor chip. The heat slug can be shaped such that a portion of the heat slug is attached to the substrate by an adhesive. The method includes: preparing a semiconductor chip having conductive bumps on the front surface of the semiconductor chip; bonding a heat slug on the backside of the semiconductor chip using a solder film; and attaching the semiconductor chip on the substrate such that the conductive bumps of the semiconductor chip contacts bonding pads of the substrate.